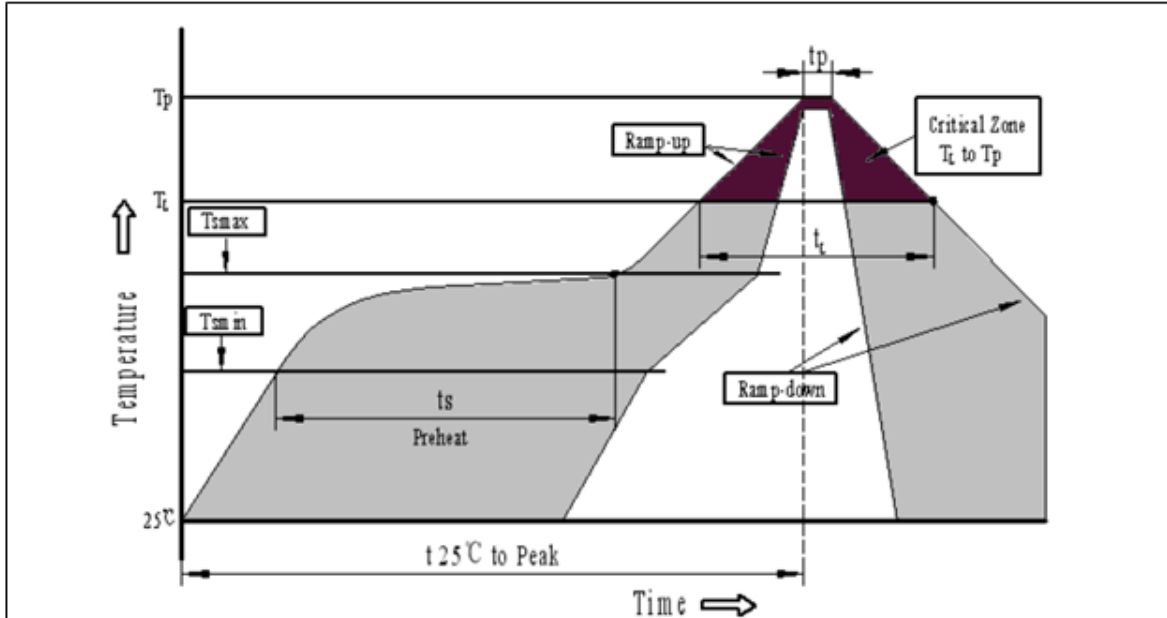


## Reflow Solder Profile for Surface Mount Devices



Profile Feature	Pb-Free Assembly
Average ramp-up rate( $T_L$ to $T_p$ )	3 °C/second max.
Preheat	
-Temperature Min.( $T_{smin}$ )	150 °C
-Temperature Min.( $T_{smax}$ )	200 °C
-Temperature Min.( $t_s$ )	60~180 seconds
$T_{smax}$ to $T_L$	
-Ramp-up Rate	3 °C/second max.
Time maintained above:	
- Temperature( $T_L$ )	217 °C
-Time( $T_L$ )	60~150 seconds
Peak temperature( $T_p$ )	245 °C+0/-5
Time within 5 °C of actual Peak temperature ( $t_p$ )	6 seconds max.
Ramp-down Rate	6 °C/second max.
Time 25 °C to Peak Temperature	8 minutes max.
<b>We suggest the customer do the reflow soldering once.</b>	